



Material Content Data Sheet



Sales Product Name	TLE7240SL			Issued		19. August 2018		
MA#	MA003429094							
Package	PG-SSOP-24-17			Weight*		146.68 mg		
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	4.342	2.96	2.96	29604	29604
leadframe	inorganic material	phosphorus	7723-14-0	0.016	0.01		106	
	non noble metal	zinc	7440-66-6	0.062	0.04		425	
	non noble metal	iron	7439-89-6	1.245	0.85		8491	
	non noble metal	copper	7440-50-8	50.568	34.48	35.38	344752	353774
wire	non noble metal	copper	7440-50-8	0.355	0.24	0.24	2417	2417
encapsulation	organic material	carbon black	1333-86-4	0.172	0.12		1175	
	plastics	epoxy resin	-	7.925	5.40		54029	
	inorganic material	silicondioxide	60676-86-0	78.043	53.21	58.73	532064	587268
leadfinish	non noble metal	tin	7440-31-5	1.680	1.15	1.15	11452	11452
plating	noble metal	silver	7440-22-4	0.365	0.25	0.25	2490	2490
glue	plastics	epoxy resin	-	0.477	0.32		3249	
	noble metal	silver	7440-22-4	1.430	0.97	1.29	9746	12995
*deviation	< 10%	Sum in total:			100.00		1000000	

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and does not use any exemption

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